



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

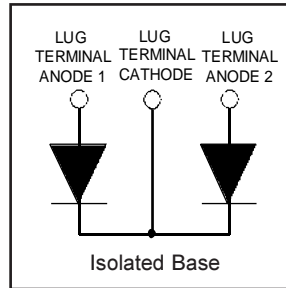


# HFA140MD60C

Ultrafast, Soft Recovery Diode

## Features

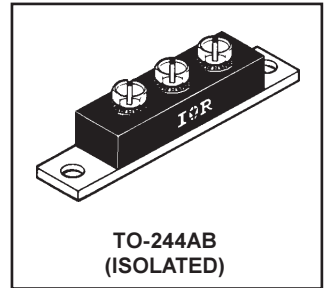
- Reduced RFI and EMI
- Reduced Snubbing
- Extensive Characterization of Recovery Parameters



$V_R = 600V$
$V_F(\text{typ.})^{\textcircled{2}} = 1.2V$
$I_{F(AV)} = 140A$
$Q_{rr}(\text{typ.}) = 360nC$
$I_{RRM}(\text{typ.}) = 8.0A$
$t_{rr}(\text{typ.}) = 35ns$
$di_{(rec)M}/dt(\text{typ.})^{\textcircled{2}} = 230A/\mu s$

## Description

HEXFRED™ diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and di/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.



## Absolute Maximum Ratings (per Leg)

	Parameter	Max.	Units
$V_R$	Cathode-to-Anode Voltage	600	V
$I_F @ T_C = 25^\circ C$	Continuous Forward Current	99	A
$I_F @ T_C = 100^\circ C$	Continuous Forward Current	48	
$I_{FSM}$	Single Pulse Forward Current <sup>①</sup>	600	
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	227	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	91	
$T_J$ $T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +150	C

## Thermal - Mechanical Characteristics

	Parameter	Min.	Typ.	Max.	Units
$R_{thJC}$	Junction-to-Case, Single Leg Conducting	—	—	0.55	°CW K/W
	Junction-to-Case, Both Legs Conducting	—	—	0.275	
$R_{thCS}$	Case-to-Sink, Flat , Greased Surface	—	0.10	—	
$Wt$	Weight	—	79 (2.8)	—	g (oz)
	Mounting Torque <sup>③</sup>	30 (3.4)	—	40 (4.6)	lbf•in
	Terminal Torque	30 (3.4)	—	40 (4.6)	(N•m)
	Vertical Pull	—	—	80	lbf•in
	2 inch Lever Pull	—	—	35	

**Note:** <sup>①</sup> Limited by junction temperature  
<sup>②</sup> 125°C

<sup>③</sup> Mounting surface must be smooth, flat, free or burrs or other protrusions. Apply a thin even film or thermal grease to mounting surface. Gradually tighten each mounting bolt in 5-10 lbf•in steps until desired or maximum torque limits are reached. Module

# HFA140MD60C

PD-40009 rev. A 01/99

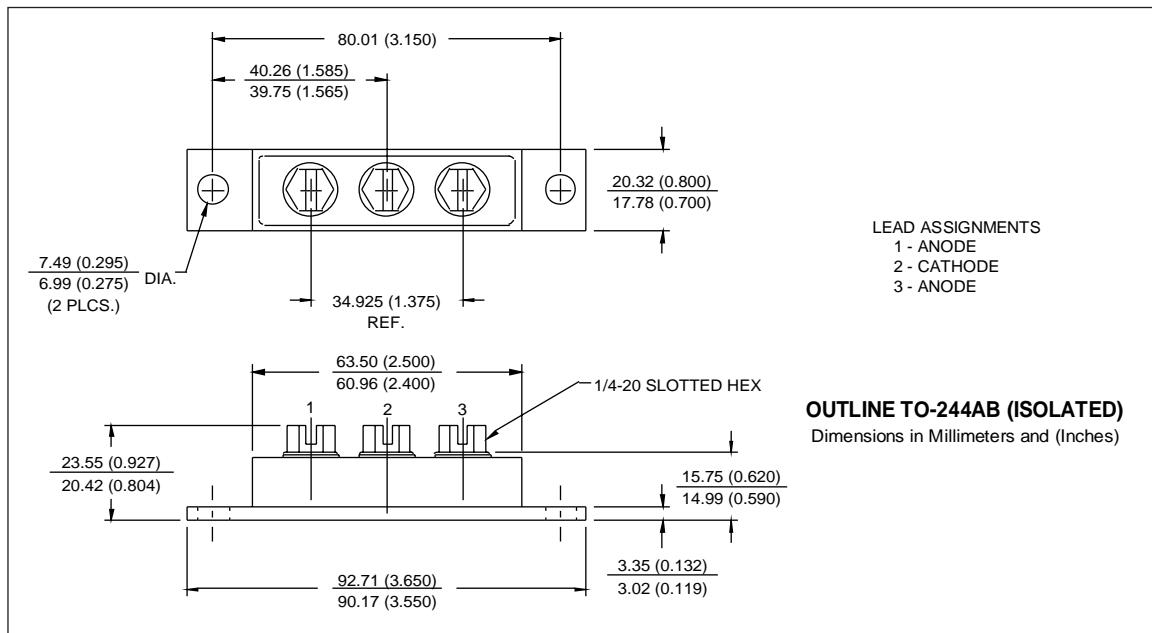
International  
**IOR** Rectifier

## Electrical Characteristics (per Leg) @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

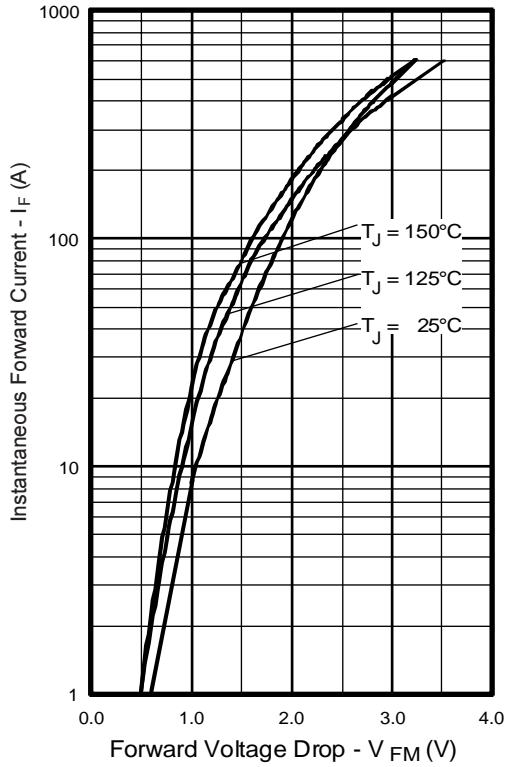
	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{BR}$	Cathode Anode Breakdown Voltage	600	—	—	V	$I_R = 100\mu\text{A}$
$V_{FM}$	Max Forward Voltage	—	1.3	1.7	V	$I_F = 70\text{A}$ $I_F = 140\text{A}$ $I_F = 70\text{A}, T_J = 125^\circ\text{C}$ See Fig. 1
		—	1.5	2.0		
		—	1.2	1.5		
$I_{RM}$	Max Reverse Leakage Current	—	3.9	15	$\mu\text{A}$	$V_R = V_R$ Rated $T_J = 125^\circ\text{C}, V_R = 480\text{V}$ See Fig. 2
		—	1300	4300		
$C_T$	Junction Capacitance	—	200	300	pF	$V_R = 200\text{V}$ See Fig. 3
$L_S$	Series Inductance	—	6.0	—	nH	From top of terminal hole to mounting plane

## Dynamic Recovery Characteristics (per Leg) @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

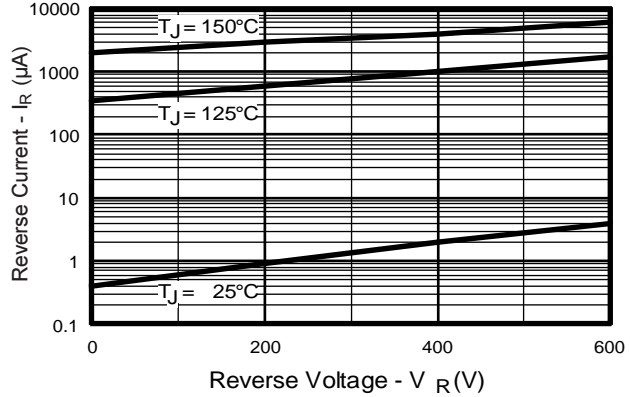
	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$t_{rr}$	Reverse Recovery Time	—	35	—	ns	$I_F = 1.0\text{A}, di/dt = 200\text{A}/\mu\text{s}, V_R = 30\text{V}$ $T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$ $I_F = 70\text{A}$ $V_R = 200\text{V}$ $di/dt = 200\text{A}/\mu\text{s}$
$t_{rr1}$	See Fig. 5, 10	—	90	140		
$t_{rr2}$		—	155	230		
$I_{RRM1}$	Peak Recovery Current	—	8.0	15	A	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$ $V_R = 200\text{V}$
$I_{RRM2}$	See Fig. 6	—	14	25		
$Q_{rr1}$	Reverse Recovery Charge	—	360	1100	nC	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$ $di/dt = 200\text{A}/\mu\text{s}$
$Q_{rr2}$	See Fig. 7	—	1100	2900		
$di_{(rec)M}/dt1$	Peak Rate of Fall of Recovery Current	—	300	—	A/ $\mu\text{s}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$
$di_{(rec)M}/dt2$	During $t_b$ See Fig. 8	—	230	—		



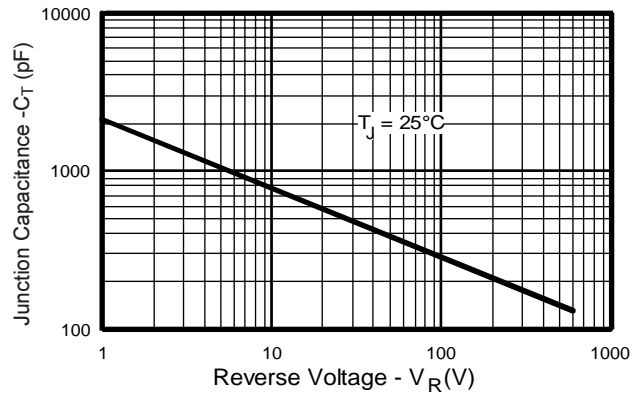




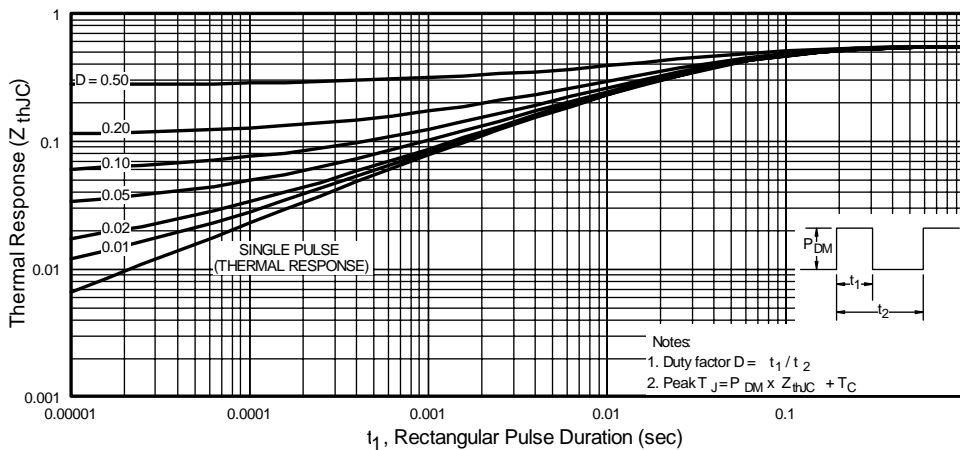
**Fig. 1** - Maximum Forward Voltage Drop vs. Instantaneous Forward Current, (per Leg)



**Fig. 2** - Typical Reverse Current vs. Reverse Voltage, (per Leg)



**Fig. 3** - Typical Junction Capacitance vs. Reverse Voltage, (per Leg)

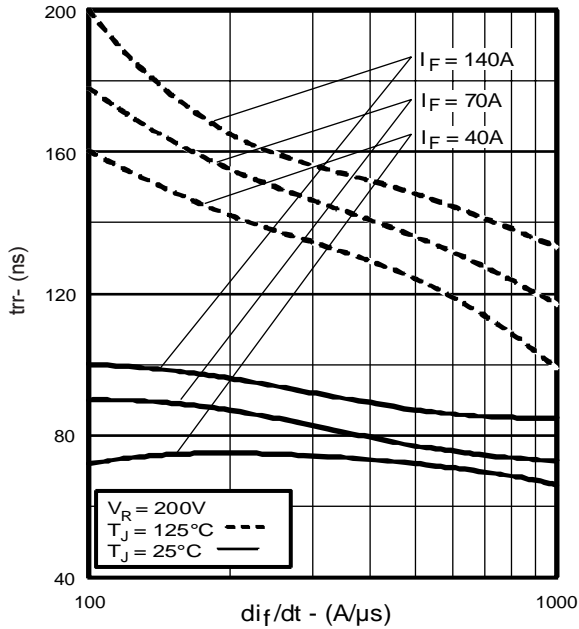


**Fig. 4** - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics, (per Leg)

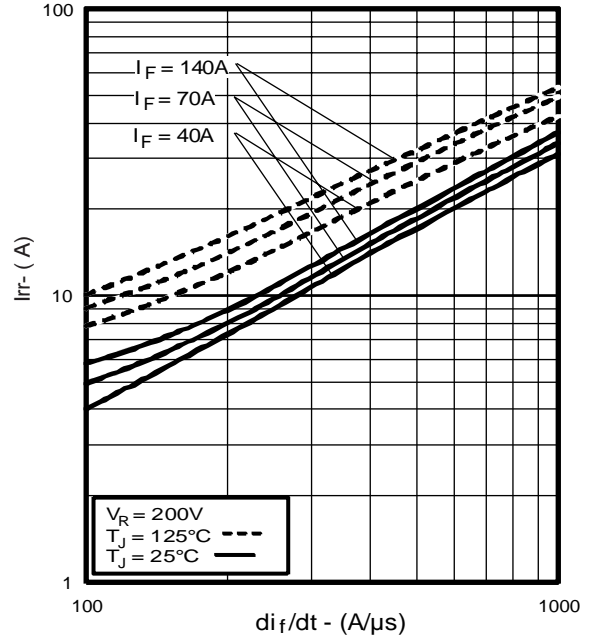
# HFA140MD60C

PD-40009 rev. A 01/99

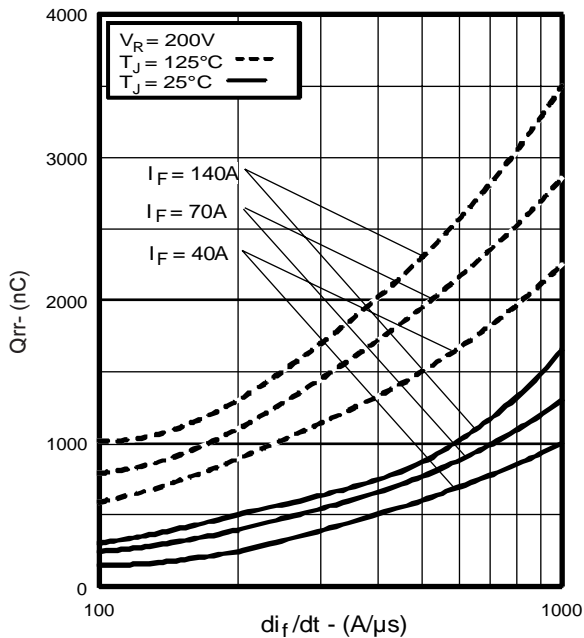
International  
IOR Rectifier



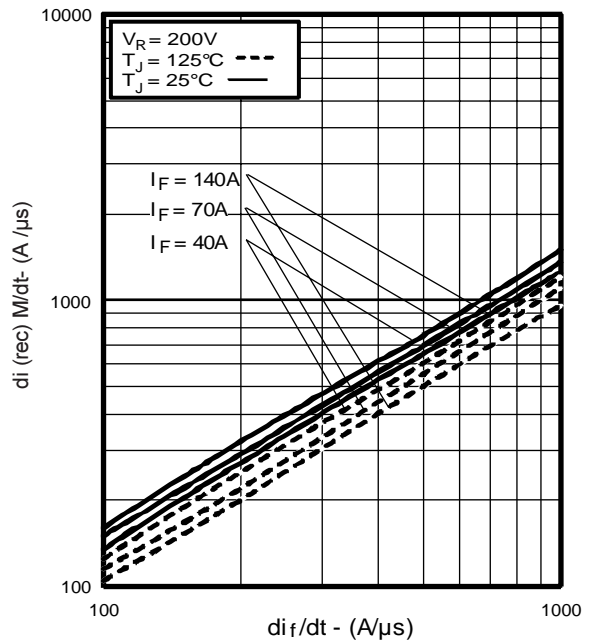
**Fig. 5** - Typical Reverse Recovery Time vs.  $di_f/dt$ , (per Leg)



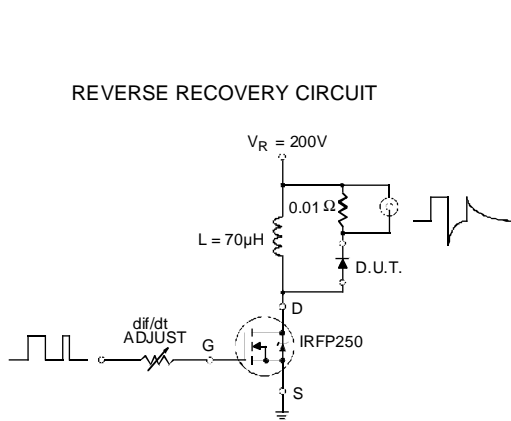
**Fig. 6** - Typical Recovery Current vs.  $di_f/dt$ , (per Leg)



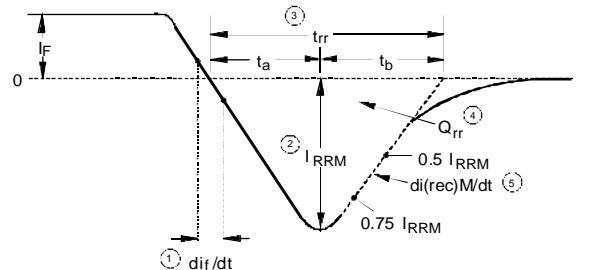
**Fig. 7** - Typical Stored Charge vs.  $di_f/dt$ , (per Leg)



**Fig. 8** - Typical  $di_{(rec)}M/dt$  vs.  $di_f/dt$ , (per Leg)



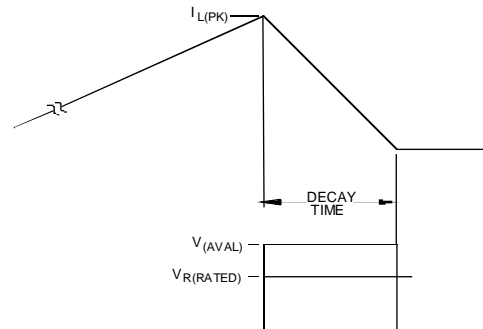
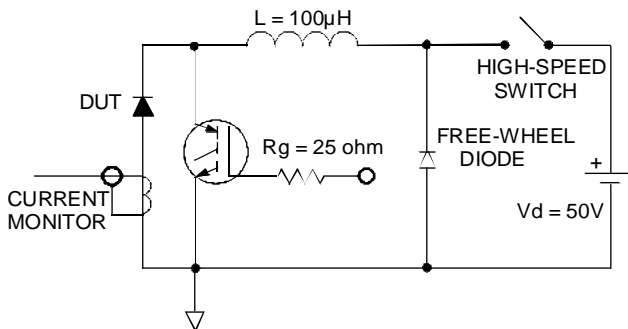
**Fig. 9** - Reverse Recovery Parameter Test Circuit



1.  $di_r/dt$  - Rate of change of current through zero crossing
2.  $I_{RRM}$  - Peak reverse recovery current
3.  $t_{rr}$  - Reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through  $0.75 I_{RRM}$  and  $0.5 I_{RRM}$  extrapolated to zero current
4.  $Q_{rr}$  - Area under curve defined by  $t_{rr}$  and  $I_{RRM}$
5.  $di_{(rec)}/dt$  - Peak rate of change of current during  $t_b$  portion of  $t_{rr}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

**Fig. 10** - Reverse Recovery Waveform and Definitions



**Fig. 11** - Avalanche Test Circuit and Waveforms